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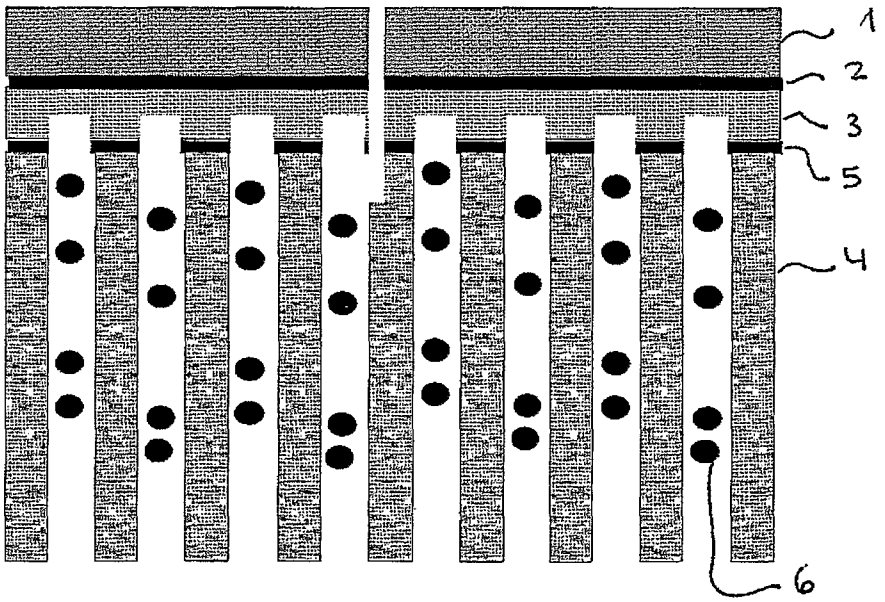
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(54) **Title:** REDUCTION OF ATTRACTION FORCES BETWEEN SILICON WAFERS



(57) **Abstract:** The present invention is related to a method for reducing attraction forces between wafers (4). This method is characterized in that it comprises the step of, after sawing and before dissolution of the adhesive (5), introducing spacers (6) between wafers (4). The invention comprises also a wafer singulation method and an agent for use in said methods .

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